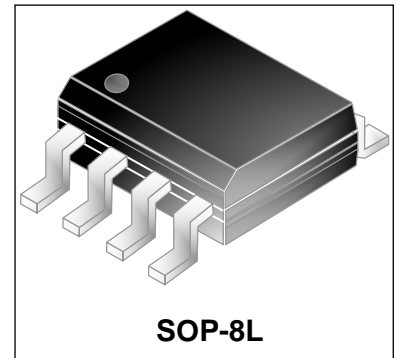


Features

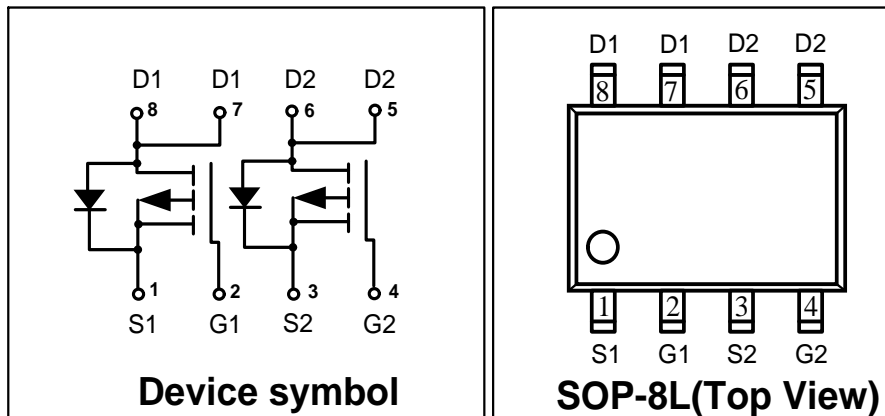
- Way-on Small Single MOSFETs
- $V_{DS} = -30V$, $I_D = -5A$
 $R_{DS(on)} < 60m\Omega @ V_{GS} = -10.0V$
 $R_{DS(on)} < 90m\Omega @ V_{GS} = -4.5V$
- Trench Power LV MOSFET Technology

Mechanical Characteristics

- SOP-8L Package
- Marking : Making Code
- RoHS Compliant



Schematic & PIN Configuration



Absolute Maximum Rating ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Breakdown Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-5	A
Pulsed Drain Current ¹	I_{DM}	-20	A
Power Dissipation	P_D	1.25	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	100	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
Gate-body Leakage current	I_{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
Gate-Threshold Voltage	V_{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.5	-2.1	V
Drain-Source On-Resistance ³	R_{DS(on)}	V _{GS} = -10V, I _D = -4.1A	-	42	60	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	57	90	
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	V _{DS} = -15V, V _{GS} = 0V, f = 1MHz	-	530	-	pF
Output Capacitance	C_{oss}		-	70	-	
Reverse Transfer Capacitance	C_{rss}		-	56	-	
Switching Characteristics⁴						
Total Gate Charge	Q_g	V _{GS} = -10V, I _D = -4.1A, V _{DS} = -15V	-	10	-	nC
Gate-Source Charge	Q_{gs}		-	2	-	
Gate-Drain Charge	Q_{gd}		-	2.8	-	
Turn-On Delay Time	t_{d(on)}	V _{GS} = -10V, V _{DD} = -15V, , R _{GEN} = 6Ω, I _D = -4.1A,	-	6.9	-	ns
Rise Time	t_r		-	12	-	
Turn-Off Delay Time	t_{d(off)}		-	19	-	
Fall Time	t_f		-	7.5	-	
Source-Drain Body Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	I _S = -1.7A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I_S		-	-	-5	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

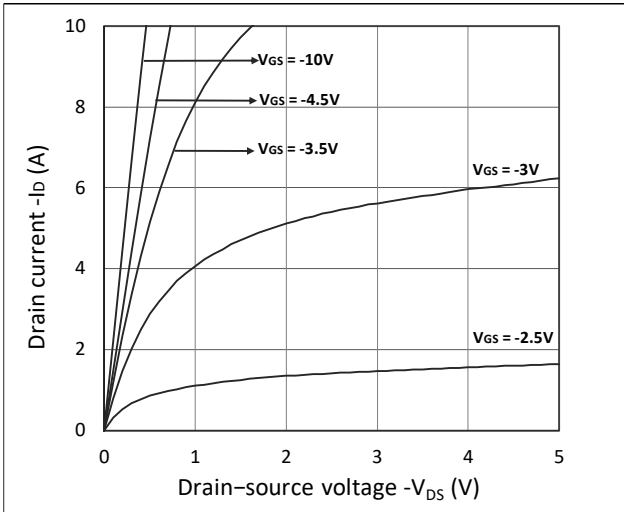


Figure 1. Output Characteristics

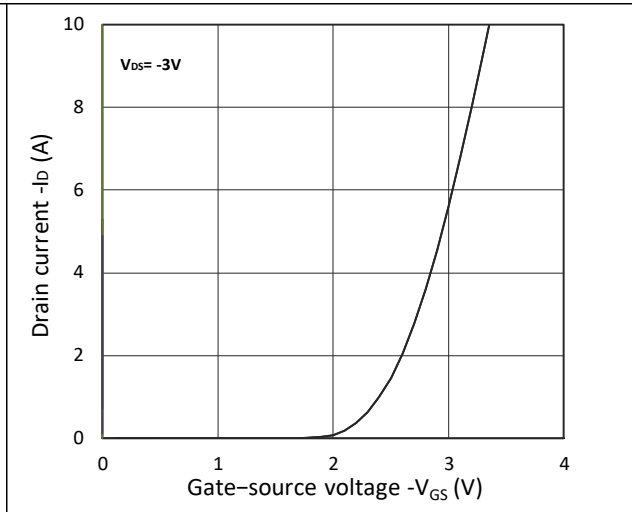


Figure 2. Transfer Characteristics

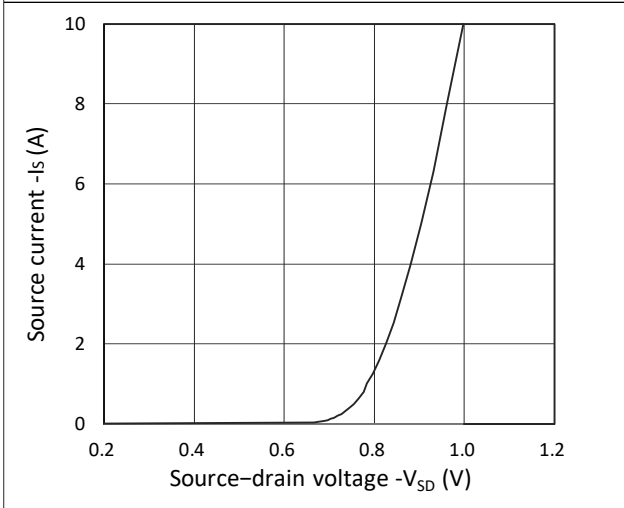


Figure 3. Forward Characteristics of Reverse

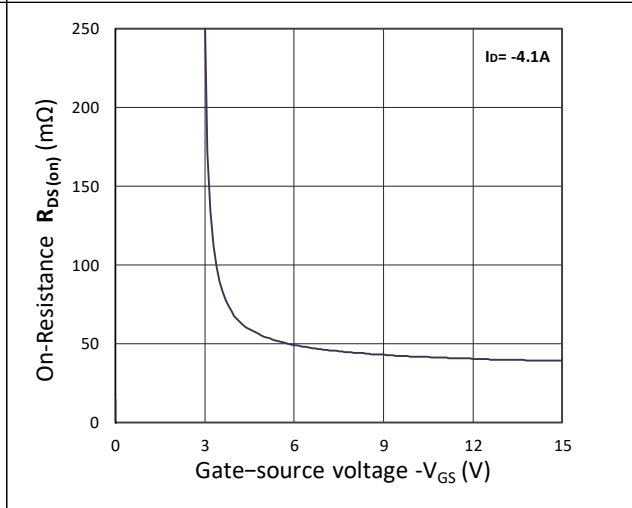


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

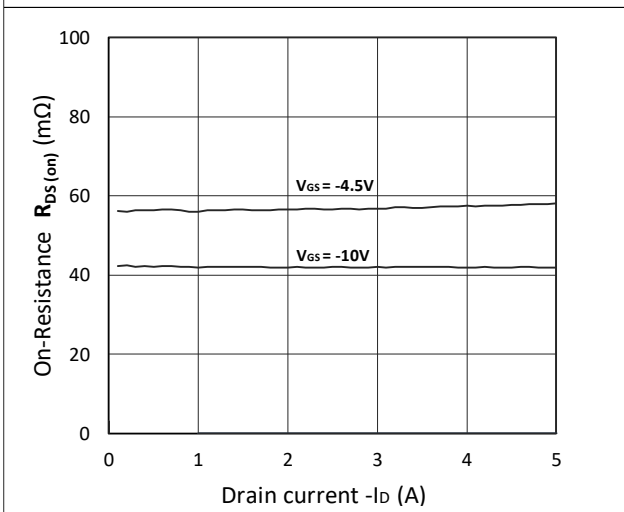


Figure 5. $R_{DS(ON)}$ vs. I_D

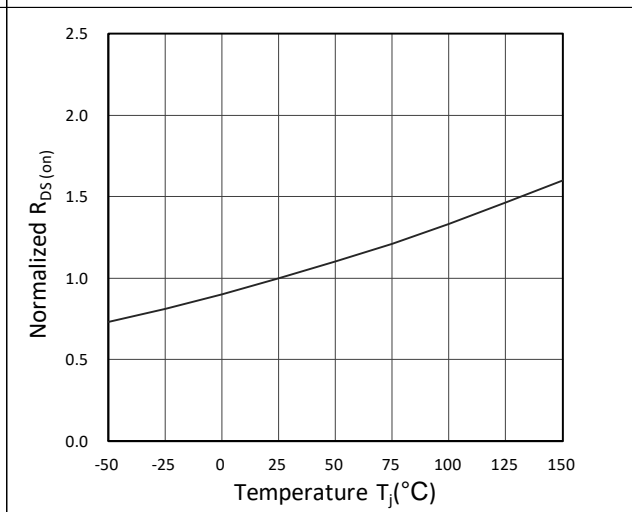


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

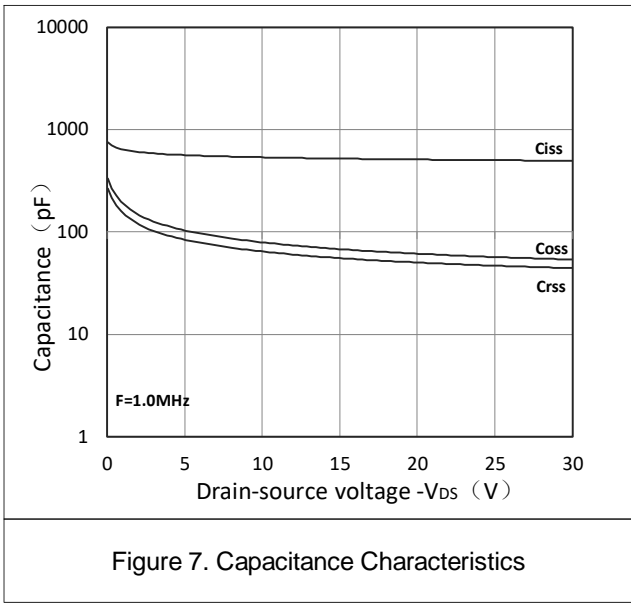


Figure 7. Capacitance Characteristics

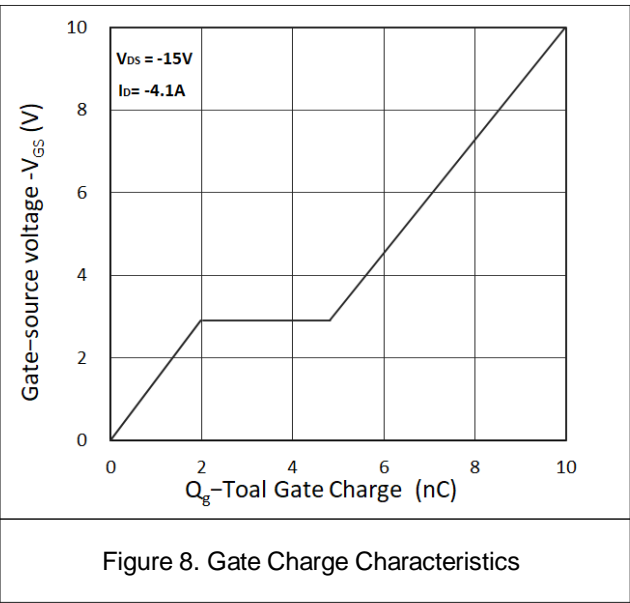


Figure 8. Gate Charge Characteristics

Outline Drawing – SOP-8L

PACKAGE OUTLINE

SOP-8L

DIMENSIONS				
SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
a1	0.05	0.25	0.002	0.010
b	0.31	0.51	0.012	0.020
b1	0.16	0.25	0.006	0.010
D	4.70	5.15	0.185	0.203
E	5.75	6.25	0.226	0.246
e	1.07	1.47	0.042	0.058
F	3.70	4.10	0.146	0.161
L	0.40	1.27	0.016	0.050

Notes

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Inches
3. Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM03DP50A
Marking Code	

Package Information

Qty: 4k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.